

L Number	Hits	Search Text	DB	Time stamp
1	1	(29/825.ccls.) and ((component or chip) with reflow) and (ACF or (anisotropic adj conductive adj film)) and ((wiring or circuit) adj board)	USPAT; US-PGPUB; IBM_TDB	2004/09/22 08:28
2	1	("6553660").PN.	USPAT; US-PGPUB; IBM_TDB	2004/09/22 08:27
3	7	(29/830,833,835,840).ccls. and ((component or chip) with reflow) and (ACF or (anisotropic adj conductive adj film)) and ((wiring or circuit) adj board)	USPAT; US-PGPUB; IBM_TDB	2004/09/22 08:30
4	3	(361/760).ccls. and ((component or chip) with reflow) and (ACF or (anisotropic adj conductive adj film)) and ((wiring or circuit) adj board)	USPAT; US-PGPUB; IBM_TDB	2004/09/22 08:31
5	3	(257/78,698).ccls. and ((component or chip) with reflow) and (ACF or (anisotropic adj conductive adj film)) and ((wiring or circuit) adj board)	USPAT; US-PGPUB; IBM_TDB	2004/09/22 08:31
9	8	("5592025"   "5612576"   "5726489"   "5736789"   "5834835"   "6016013"   "6057597"   "6064114").PN.	USPAT	2004/09/22 08:32
-	2	(("6,222,281") or ("6,265,770")).PN.	USPAT; US-PGPUB; IBM_TDB	2004/09/21 11:52
-	1	(kobayashi-yukihisa).in.	USPAT; US-PGPUB; IBM_TDB	2004/09/21 09:40
-	313	reflow and (ACF or (anisotropic adj conductive adj film))	USPAT; US-PGPUB; IBM_TDB	2004/09/21 11:53
-	218	reflow and (ACF or (anisotropic adj conductive adj film)) and ((wiring or circuit) adj board)	USPAT; US-PGPUB; IBM_TDB	2004/09/21 11:54
-	73	((component or chip) with reflow) and (ACF or (anisotropic adj conductive adj film)) and ((wiring or circuit) adj board)	USPAT; US-PGPUB; IBM_TDB	2004/09/21 18:39
-	19	((component or chip) with reflow) and (ACF or (anisotropic adj conductive adj film)) with (conductive adj particle) and ((wiring or circuit) adj board)	USPAT; US-PGPUB; IBM_TDB	2004/09/21 13:52
-	1	(component or chip) and reflow same ((ACF or (anisotropic adj conductive adj film)) with (conductive adj particle)) and ((wiring or circuit) adj board)	USPAT; US-PGPUB; IBM_TDB	2004/09/21 13:53
-	74	(component or chip) and reflow and (ACF or (anisotropic adj conductive adj film)) with (conductive adj particle) and ((wiring or circuit) adj board)	USPAT; US-PGPUB; IBM_TDB	2004/09/21 14:00
-	57	(component or chip) and (solder with reflow) and (ACF or (anisotropic adj conductive adj film)) with (conductive adj particle) and ((wiring or circuit) adj board)	USPAT; US-PGPUB; IBM_TDB	2004/09/21 14:01
-	9	("5502889"   "5525205"   "5679730"   "5727310"   "5822030"   "5861661"   "5978203"   "6111628"   "6190578").PN.	USPAT	2004/09/21 14:26
-	8	(29/832.ccls.) and ((component or chip) with reflow) and (ACF or (anisotropic adj conductive adj film)) and ((wiring or circuit) adj board)	USPAT; US-PGPUB; IBM_TDB	2004/09/21 18:44